

SYSTEM FOR PROVIDING AN OPEN-CAVITY LOW PROFILE ENCAPSULATED SEMICONDUCTOR PACKAGE

ABSTRACT OF THE INVENTION

System for providing an open-cavity semiconductor package. The system
5 includes a method for wire bonding a finger sensor die to an external circuit. The finger
sensor die includes a sensor array having one or more die contacts that are wire bonded to
one or more external contacts of the external circuit so that a usable portion of the sensor
array is maximized. The method comprises steps of forming a ball at a first end of a
bonding wire, forming an electrically conductive connection between the ball and a
10 selected external contact of the external circuit, extending the bonding wire to a selected
die contact so as to form a wire loop having a low loop height, and forming an
electrically conductive stitch connection between a second end of the bonding wire and
the selected die contact.

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